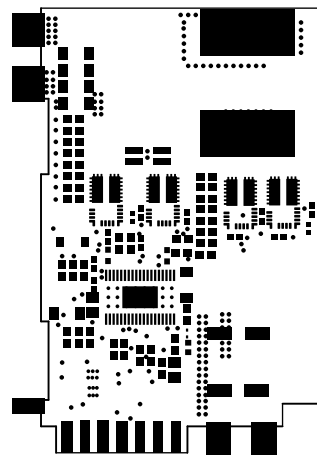
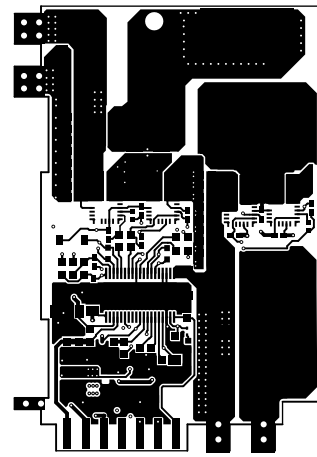


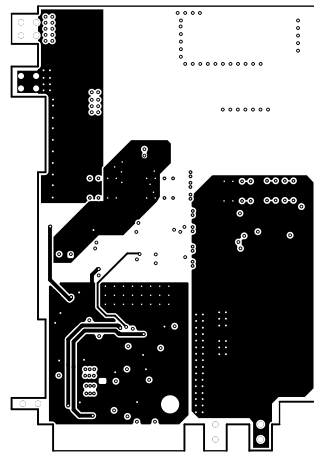
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP23377	REV: B	SUN REV: Not in version control
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 2024/10/8	시간 09:06:46	TEXAS INSTRUMENTS



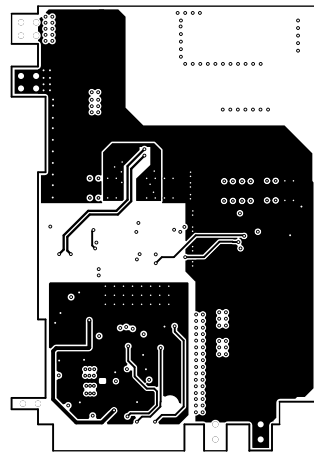
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP23377	REV: B	SUN REV: Not in version control
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 2024/10/8	시간 09:06:46	TEXAS INSTRUMENTS



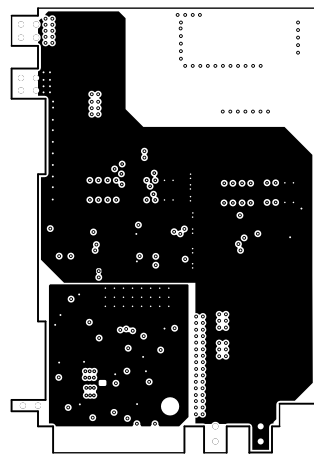
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP23377	REV: B	SUN REV: Not in version control
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 2024/10/8	시간 09:06:47	TEXAS INSTRUMENTS



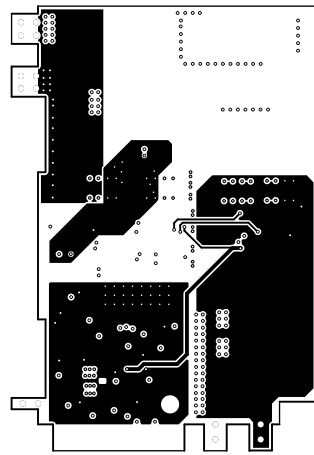
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP23377	REV: B	SUN REV: Not in version control
LAYER NAME =	TID #: N/A		
PLOT NAME = Signal Layer 1	GENERATED : 2024/10/8	09:06:47	TEXAS INSTRUMENTS



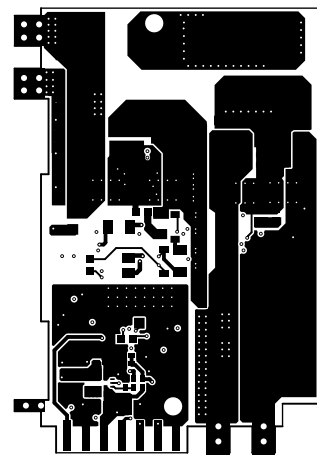
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP23377	REV: B	SUN REV: Not in version control
LAYER NAME =	TID #: N/A		
PLOT NAME = Signal Layer 2	GENERATED : 2024/10/8	09:06:47	TEXAS INSTRUMENTS



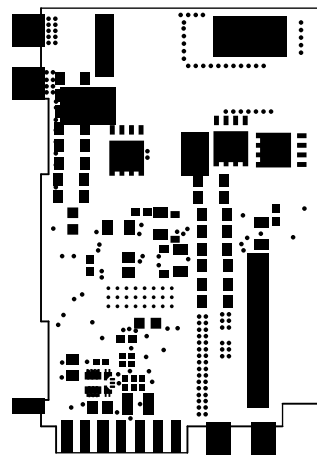
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP23377	REV: B	SUN REV: Not in version control
LAYER NAME =	TID #: N/A		
PLOT NAME = Signal Layer 3	GENERATED : 2024/10/8	09:06:47	TEXAS INSTRUMENTS



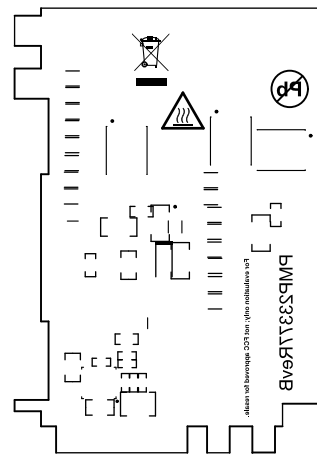
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP23377	REV: B	SUN REV: Not in version control
LAYER NAME =	TID #: N/A		
PLOT NAME = Signal Layer 4	GENERATED : 2024/10/8	09:06:47	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP23377	REV: B	SUN REV: Not in version control
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 2024/10/8	시간 09:06:47	TEXAS INSTRUMENTS

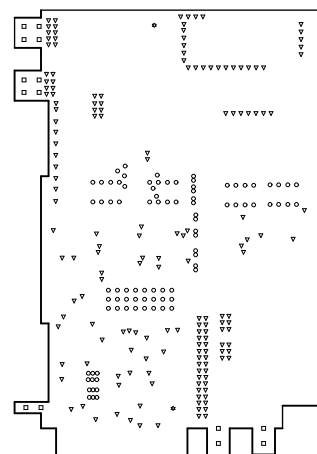


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP23377	REV: B	SUN REV: Not in version control
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 2024/10/8	시간 09:06:47	TEXAS INSTRUMENTS

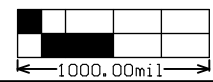
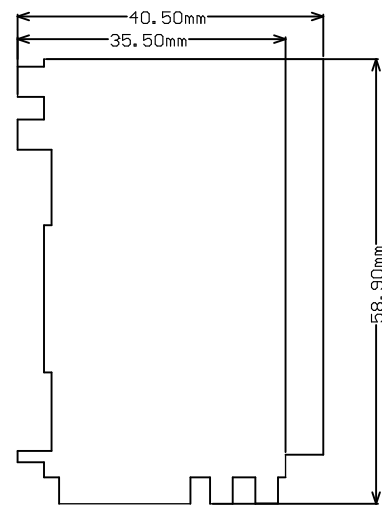


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP23377	REV: B	SUN REV: Not in version control
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 2024/10/8	시간 09:06:47	TEXAS INSTRUMENTS

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)
☆	2	78.74mil (2.000mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0h200			
□	14	31.50mil (0.800mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v80h80			
○	89	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	(Mixed)			
▽	171	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	(Mixed)			
	276 Total										



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP23377	REV: B	SUN REV: Not in version control
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 2024/10/8	ÀÛÀ 09:06:47	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP23377	REV: B	SUN REV: Not in version control
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 2024/10/8	시간 09:06:47	TEXAS INSTRUMENTS

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